

Features

- 650-Volt Schottky Rectifier
- Zero Reverse Recovery Current
- Zero Forward Recovery Voltage
- High-Frequency Operation
- Temperature-Independent Switching Behavior
- Extremely Fast Switching
- Positive Temperature Coefficient on V_F

Benefits

- Replace Bipolar with Unipolar Rectifiers
- Essentially No Switching Losses
- Higher Efficiency
- Reduction of Heat Sink Requirements
- Parallel Devices Without Thermal Runaway

Applications

- Switch Mode Power Supplies
- Power Factor Correction
- Motor Drives

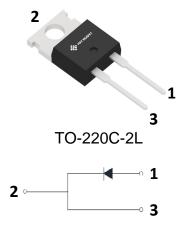


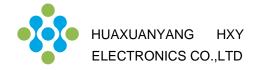


Part Number	Package	Marking
HC3D20065A	TO-220C-2L	HC3D20065A

Maximum Ratings ($T_c = 25$ °C unless otherwise specified)

Symbol	Parameter	Value	Unit	Test Conditions
V _{RRM}	Repetitive Peak Reverse Voltage	650	٧	
V _{RSM}	Surge Peak Reverse Voltage	650	٧	
V _{DC}	DC Blocking Voltage	650	V	
I _F	Continuous Forward Current	20	А	T _c =125°C
I _{FRM}	Repetitive Peak Forward Surge Current	81	А	T _c =110°C, t _p =10 ms, Half Sine Wave
I _{FSM}	Non-Repetitive Peak Forward Surge Current	123 104	А	T_c =25°C, t_p = 10 ms, Half Sine Wave T_c =150°C, t_p = 10 ms, Half Sine Wave
I _{F,Max}	Non-Repetitive Peak Forward Surge Current	450	А	T_c =25°C, t_p = 10 µs, Pulse
P _{tot}	Power Dissipation	115	W	T _c =25°C
T_J , T_{stg}	Operating Junction and Storage Temperature	-55 to +175	°C	





Electrical Characteristics

Symbol	Parameter	Тур.	Max.	Unit	Test Conditions
V _F	Forward Voltage	1.35 1.5	1.5 -	V	I _F = 20 A ,T _J =25°C I _F = 20 A ,T _J =175°C
I _R	Reverse Current	0.06 12	100 -	μΑ	V _R = 650 V T _J =25°C V _R = 650 V T _J =175°C
Q _c	Total Capacitive Charge	24		nC	$V_R = 400 \text{ V, I}_F = 10 \text{ A}$ $di/dt = 500 \text{ A}/\mu\text{s}$ $T_J = 25^{\circ}\text{C}$
С	Total Capacitance	1000 91		pF	V _R = 0 V, T _J = 25°C, f = 1 MHz V _R = 400 V, T _J = 25°C, f = 1 MHz
E _{ava}	Non-repetetive Avaranche Energy	220		mJ	L=1mH

Note: This is a majority carrier diode, so there is no reverse recovery charge.

Thermal Characteristics

Symbol	Parameter	Тур.	Unit
$R_{_{\theta JC}}$	Thermal Resistance from Junction to Case	0.87	°C/W

Typical Performance

Fig.1 V_F - I_F Characteristics

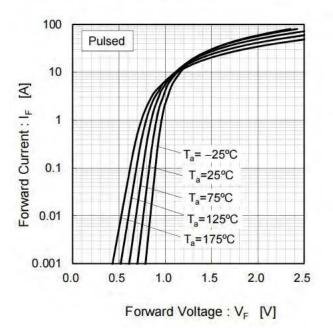
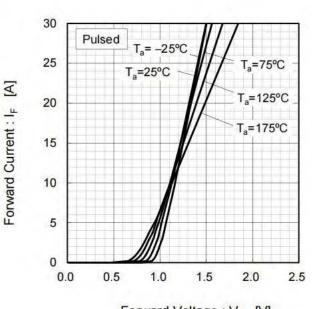


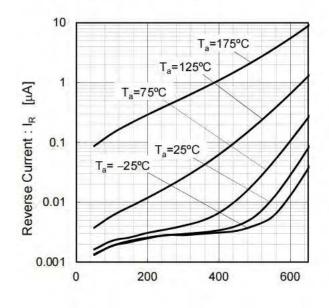
Fig. 2 V_F - I_F Characteristics





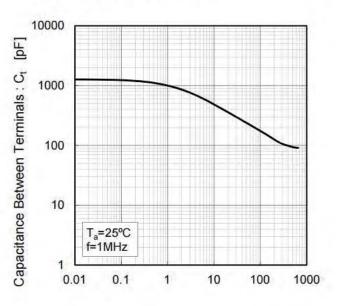
Typical Performance

Fig. 3 V_R - I_R Characteristics



Reverse Voltage : V_R [V]

Fig.4 V_R-C_t Characteristics



Reverse Voltage : V_R [V]

Fig.5 Typical Transient Thermal Resistance vs. Pulse Width

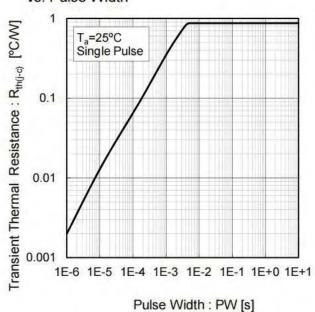
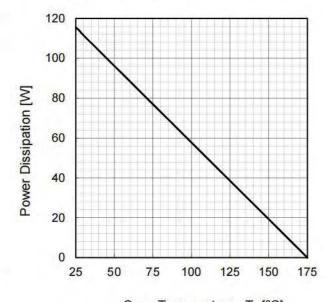


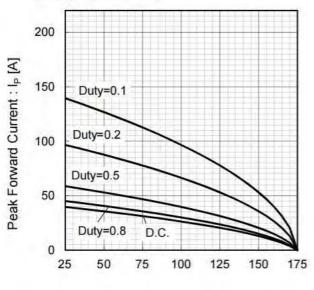
Fig.6 Power Dissipation



Case Temperature : T_c [°C]

Typical Performance

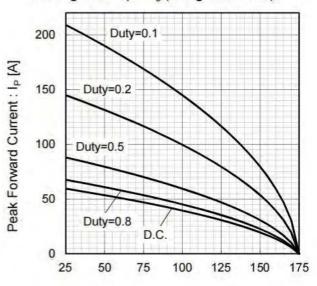
Fig.7*3 Maximum peak forward current derating curve $I_P - T_c$



Case Temperature : T_c [°C]

 $^{\star}3$ Based on max Vf, max R_{th(j-c)} Valid for switching of above 10kHz, excluding D.C. curve.

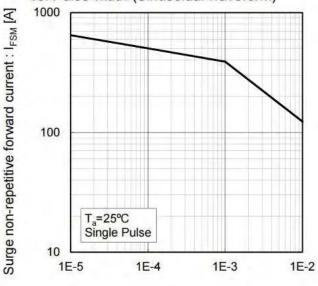
Fig.8*4 Typical peak forward current derating curve I_P - T_c (Not guaranteed)



Case Temperature : T_c [°C]

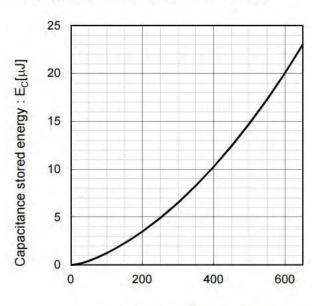
*4 Based on typ Vf, typ R_{th(j-c)} Typical value, not guaranteed Valid for switching of above 10kHz, excluding D.C. curve

Fig.9 Surge non-repetitive forward current vs. Pulse width (Sinusoidal waveform)



Pulse Width: PW[s]

Fig. 10 Typical capacitance store energy

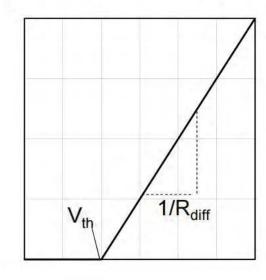


Reverse Voltage : V_R [V]

Typical Performance

Forward Current : I_F

Fig.11 Equivalent forward current curve



Forward Voltage : V_F

$$V_F = V_{th} + R_{diff} I_F$$

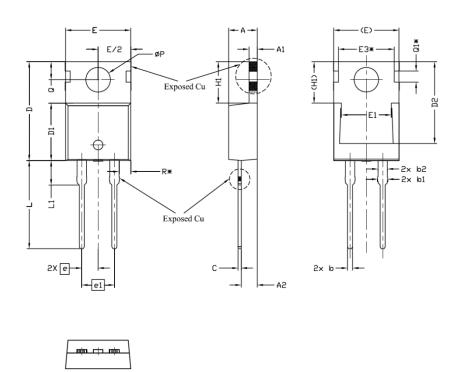
$$V_{th}(T_j) = a_0 + a_1 T_j$$

 $R_{diff}(T_j) = b_0 + b_1 T_j + b_2 T_j^2$

Symbol	Typical Value	Unit
a_0	9.66E-01	V
a ₁	- 1.10E-03	V/°C
b ₀	1.76E-02	Ω
b ₁	3.73E-05	Ω/°C
b ₂	3.84E-07	$\Omega/^{\circ}C^{2}$

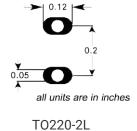
 T_j in °C; -55 °C < T_j < 175°C ; I_F < 40A

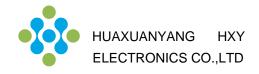
Package Information TO-220C-2L



	DIMENSIONS			
SYMBOL	MIN.	NOM.	MAX.	NOTES
Α	4,24	4,44	4,64	
A1	1.15	1.27	1.40	
A2	2.30	2.48	2.70	
Ф	0.70	0.80	0.90	
b1	1.20	1.55	1.75	
b2	1.20	1.45	1.70	
С	0.40	0.50	0.60	
D	14.70	15.37	16.00	4
D1	8.82	8.92	9,02	
D2	12.43	12.73	12.83	5
ш	9.96	10.16	10.36	4,5
E1	6,86	7.77	8,89	5
E3*		8.70REF.		
e	2,54BSC			
e1	5.08BSC			
H1	6.30	6.45	6.60	5,6
L	13.47	13.72	13,97	
L1	3.60	3.80	4.00	
ØP	3.75	3.84	3,93	
Q	2,60	2,80	3,00	
Q1*	1.73REF			
R*	1.82REF.			

Recommended Solder Pad Layout





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